

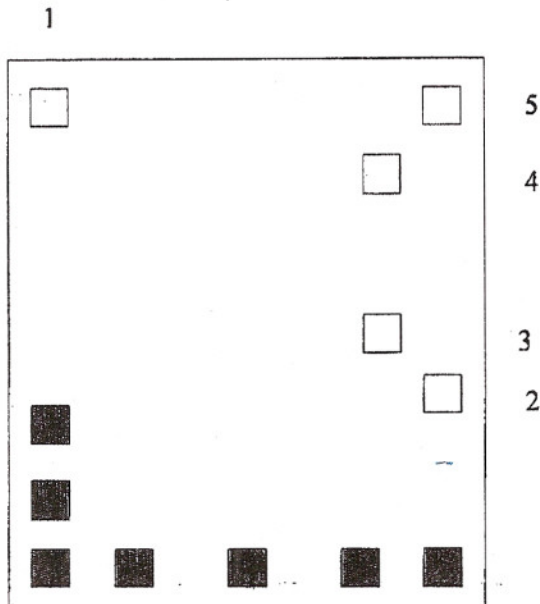


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PAD FUNCTIONS

1. CATHODE
2. ANODE
3. REFERENCE
4. REFERENCE
5. ANODE



NOTE : IT IS ONLY NECESSARY TO BOND TO ONE OF THE TWO AVAILABLE PADS FOR THE ANODE OR REFERENCE CONNECTIONS

The information given is believed to be correct at the time of issue.

Please verify your requirements prior to commencement of any assembly process, as no liability for omission or error can be accepted.

Chip back potential is the level at which bulk silicon is maintained either by bond pad connection or in some cases the potential to which the chip back must be connected if stated above.

Note: 1 mil = 0.001inch

APPROVED

G Bibby

DATE: 8 Feb 2005

SERIAL NUMBER

006294

TLC431

ON SEMICONDUCTOR

DIE INFORMATION

DIMENSIONS (Mils): 53 x 48 x 14
 BOND PADS (Mils): 4 x 4
 MASK REF: 431B
 GEOMETRY:
 BACK POTENTIAL: ANODE

METALLISATION

TOP: Al
 BACK: Si